

# IPTC063N15NM5-VB Datasheet

## N-Channel 150 V (D-S) MOSFET

### PRODUCT SUMMARY

| $V_{DS}$ (V) | $R_{DS(on)}$ ( $\Omega$ ) MAX. | $I_D$ (A) | $Q_g$ (TYP.) |
|--------------|--------------------------------|-----------|--------------|
| 150          | 0.0062 at $V_{GS} = 10$ V      | 150       | 100 nC       |

### FEATURES

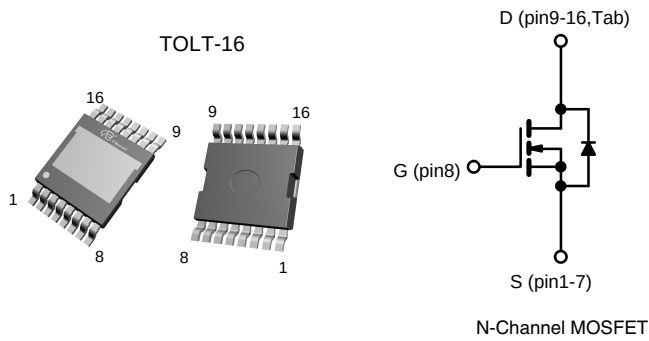
- SGT technology Power MOSFET
- Maximum 175°C junction temperature
- 100 %  $R_g$  and UIS tested



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### APPLICATIONS

- Power supplies:
  - Uninterruptible power supplies
  - AC/DC switch-mode power supplies
  - Lighting
- Synchronous rectification
- DC/DC converter
- Motor drive switch
- DC/AC inverter
- Solar micro inverter
- Class D audio amplifier



### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ , unless otherwise noted)

| PARAMETER                                              | SYMBOL                    | LIMIT                  | UNIT             |
|--------------------------------------------------------|---------------------------|------------------------|------------------|
| Drain-Source Voltage                                   | $V_{DS}$                  | 150                    | V                |
| Gate-Source Voltage                                    | $V_{GS}$                  | $\pm 20$               |                  |
| Continuous Drain Current ( $T_J = 150^\circ\text{C}$ ) | $T_C = 25^\circ\text{C}$  | $I_D$ 150              | A                |
|                                                        | $T_C = 100^\circ\text{C}$ | 120                    |                  |
| Pulsed Drain Current ( $t = 100 \mu\text{s}$ )         | $I_{DM}$                  | 600                    |                  |
| Avalanche Current                                      | $I_{AS}$                  | 75                     |                  |
| Single Avalanche Energy <sup>a</sup>                   | $E_{AS}$                  | 1370                   | mJ               |
| Maximum Power Dissipation <sup>a</sup>                 | $T_C = 25^\circ\text{C}$  | $P_D$ 375 <sup>b</sup> | W                |
|                                                        | $T_C = 100^\circ\text{C}$ | 187.5 <sup>b</sup>     |                  |
| Operating Junction and Storage Temperature Range       | $T_J, T_{stg}$            | -55 to +175            | $^\circ\text{C}$ |

### THERMAL RESISTANCE RATINGS

| PARAMETER                                    | SYMBOL     | LIMIT | UNIT                      |
|----------------------------------------------|------------|-------|---------------------------|
| Junction-to-Ambient (PCB Mount) <sup>c</sup> | $R_{thJA}$ | 62    | $^\circ\text{C}/\text{W}$ |
| Junction-to-Case (Drain)                     | $R_{thJC}$ | 0.4   |                           |

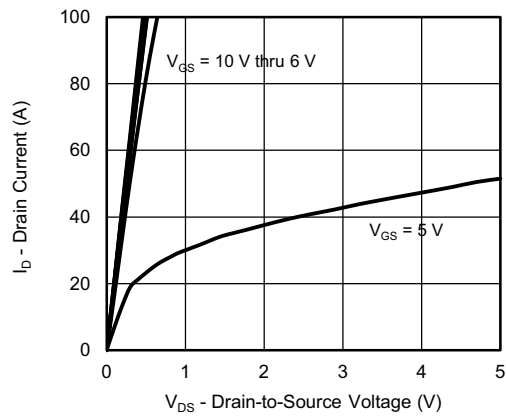
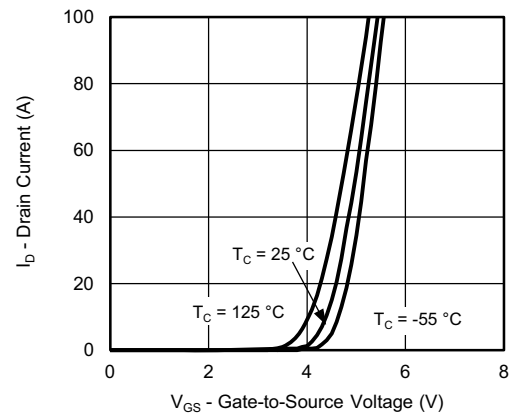
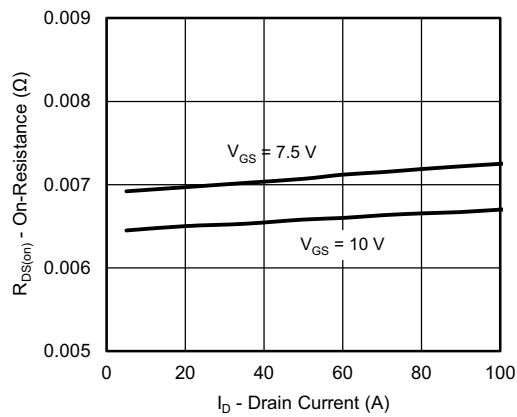
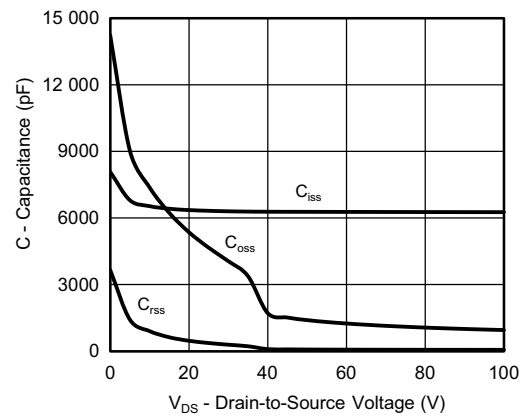
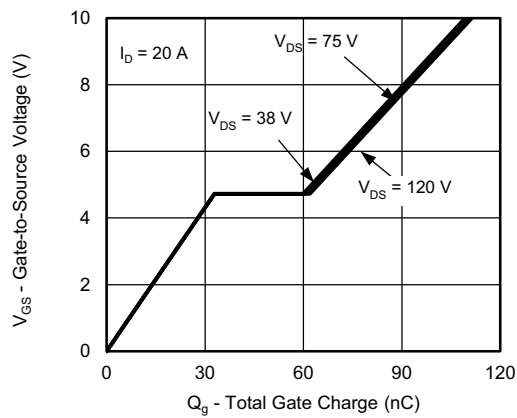
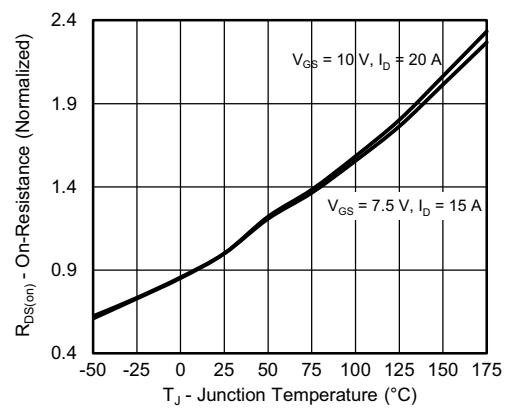
#### Notes

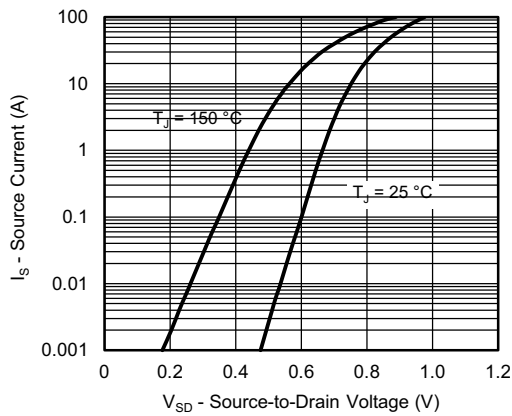
- Duty cycle  $\leq 1\%$ .
- See SOA curve for voltage derating.
- When mounted on 1" square PCB (FR4 material).

| SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)                           |                      |                                                                                                                         |      |        |       |      |
|-------------------------------------------------------------------------------------------|----------------------|-------------------------------------------------------------------------------------------------------------------------|------|--------|-------|------|
| PARAMETER                                                                                 | SYMBOL               | TEST CONDITIONS                                                                                                         | MIN. | TYP.   | MAX.  | UNIT |
| Static                                                                                    |                      |                                                                                                                         |      |        |       |      |
| Drain-Source Breakdown Voltage                                                            | V <sub>DS</sub>      | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA                                                                          | 150  | -      | -     | V    |
| Gate Threshold Voltage                                                                    | V <sub>GS(th)</sub>  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA                                                             | 2    | 3      | 4     |      |
| Gate-Body Leakage                                                                         | I <sub>GSS</sub>     | V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V                                                                         | -    | -      | ± 250 | nA   |
| Zero Gate Voltage Drain Current                                                           | I <sub>DSS</sub>     | V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V                                                                          | -    | -      | 1     | μA   |
|                                                                                           |                      | V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C                                                 | -    | -      | 100   |      |
|                                                                                           |                      | V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150°C                                                  | -    | -      | 5     | mA   |
| On-State Drain Current <sup>a</sup>                                                       | I <sub>D(on)</sub>   | V <sub>DS</sub> ≥ 10 V, V <sub>GS</sub> = 10 V                                                                          | 90   | -      | -     | A    |
| Drain-Source On-State Resistance <sup>a</sup>                                             | R <sub>DS(on)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 60 A                                                                           | -    | 0.0062 | -     | Ω    |
|                                                                                           |                      | V <sub>GS</sub> = 7.5 V, I <sub>D</sub> = 25 A                                                                          | -    | 0.0069 | -     |      |
| Forward Transconductance <sup>a</sup>                                                     | g <sub>fs</sub>      | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A                                                                           | -    | 60     | -     | S    |
| Dynamic <sup>b</sup>                                                                      |                      |                                                                                                                         |      |        |       |      |
| Input Capacitance                                                                         | C <sub>iss</sub>     | V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 75V, f = 1 MHz                                                                 | -    | 5500   | -     | pF   |
| Output Capacitance                                                                        | C <sub>oss</sub>     |                                                                                                                         | -    | 846    | -     |      |
| Reverse Transfer Capacitance                                                              | C <sub>rss</sub>     |                                                                                                                         | -    | 32     | -     |      |
| Total Gate Charge <sup>c</sup>                                                            | Q <sub>g</sub>       | V <sub>DS</sub> = 7.5 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A                                                  | -    | 100    | -     | nC   |
| Gate-Source Charge <sup>c</sup>                                                           | Q <sub>gs</sub>      |                                                                                                                         | -    | 30     | -     |      |
| Gate-Drain Charge <sup>c</sup>                                                            | Q <sub>gd</sub>      |                                                                                                                         | -    | 25     | 35    |      |
| Gate Resistance                                                                           | R <sub>g</sub>       | f = 1 MHz                                                                                                               | -    | 0.9    | 1.2   | Ω    |
| Turn-On Delay Time <sup>c</sup>                                                           | t <sub>d(on)</sub>   | V <sub>DD</sub> = 75 V, R <sub>L</sub> = 1.66 Ω<br>I <sub>D</sub> ≅ 50 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 1 Ω | -    | 18     | -     | ns   |
| Rise Time <sup>c</sup>                                                                    | t <sub>r</sub>       |                                                                                                                         | -    | 50     | -     |      |
| Turn-Off Delay Time <sup>c</sup>                                                          | t <sub>d(off)</sub>  |                                                                                                                         | -    | 75     | -     |      |
| Fall Time <sup>c</sup>                                                                    | t <sub>f</sub>       |                                                                                                                         | -    | 55     | -     |      |
| Drain-Source Body Diode Ratings and Characteristics <sup>b</sup> (T <sub>C</sub> = 25 °C) |                      |                                                                                                                         |      |        |       |      |
| Pulsed Current (t = 100 μs)                                                               | I <sub>SM</sub>      |                                                                                                                         | -    | -      | 100   | A    |
| Forward Voltage <sup>a</sup>                                                              | V <sub>SD</sub>      | I <sub>F</sub> = 500 A, V <sub>GS</sub> = 0 V                                                                           | -    | 0.84   | 1.3   | V    |
| Reverse Recovery Time                                                                     | t <sub>rr</sub>      | I <sub>F</sub> = 50 A, di/dt = 100 A/μs                                                                                 | -    | 85     | 120   | ns   |
| Peak Reverse Recovery Charge                                                              | I <sub>RM(REC)</sub> |                                                                                                                         | -    | 11     | 20    | A    |
| Reverse Recovery Charge                                                                   | Q <sub>rr</sub>      |                                                                                                                         | -    | 0.8    | 1.0   | μC   |

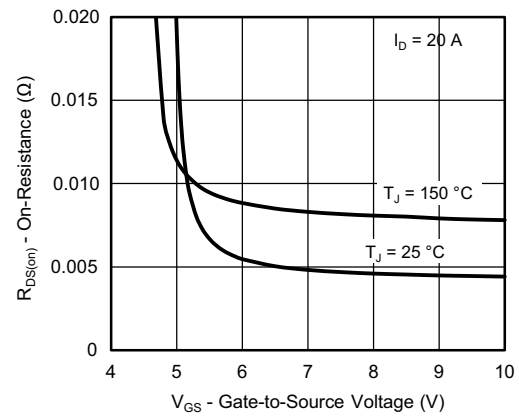
**Notes**

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
 b. Guaranteed by design, not subject to production testing.  
 c. Independent of operating temperature.

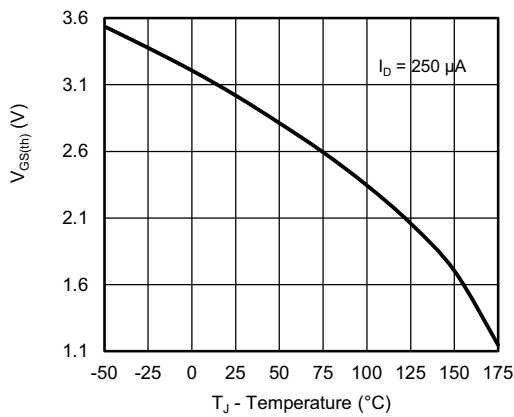
**TYPICAL CHARACTERISTICS** ( $T_C = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

**Output Characteristics**

**Transfer Characteristics**

**On-Resistance vs. Drain Current and Gate Voltage**

**Capacitance**

**Gate Charge**

**On-Resistance vs. Junction Temperature**



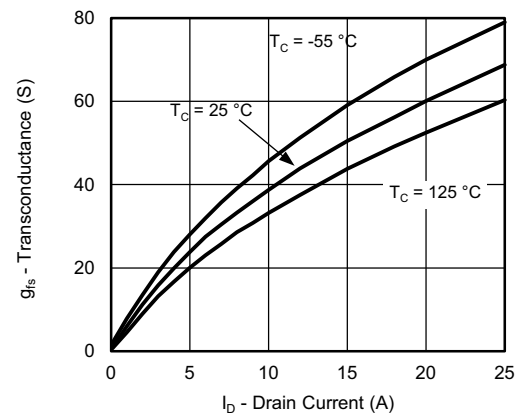
Source-Drain Diode Forward Voltage



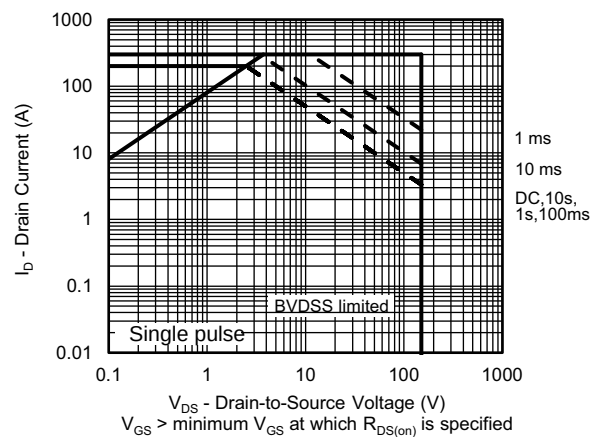
On-Resistance vs. Gate-to-Source Voltage



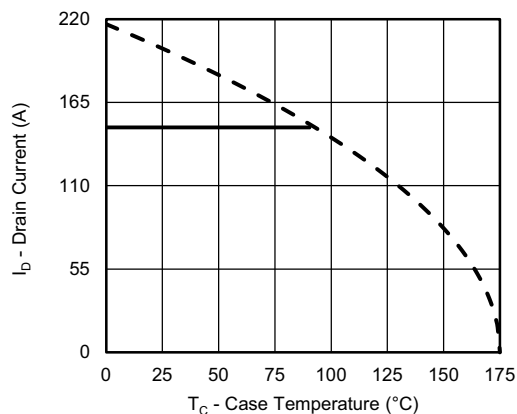
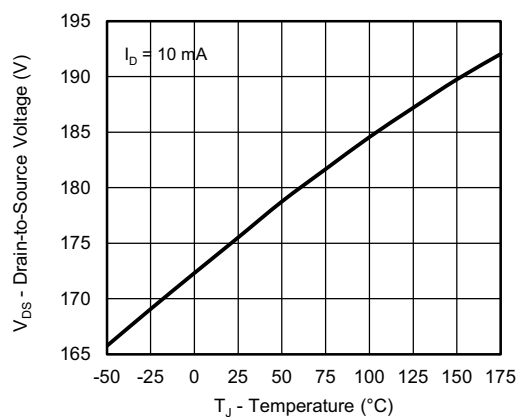
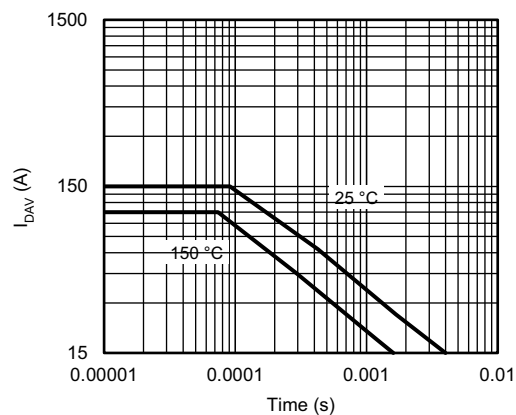
Threshold Voltage



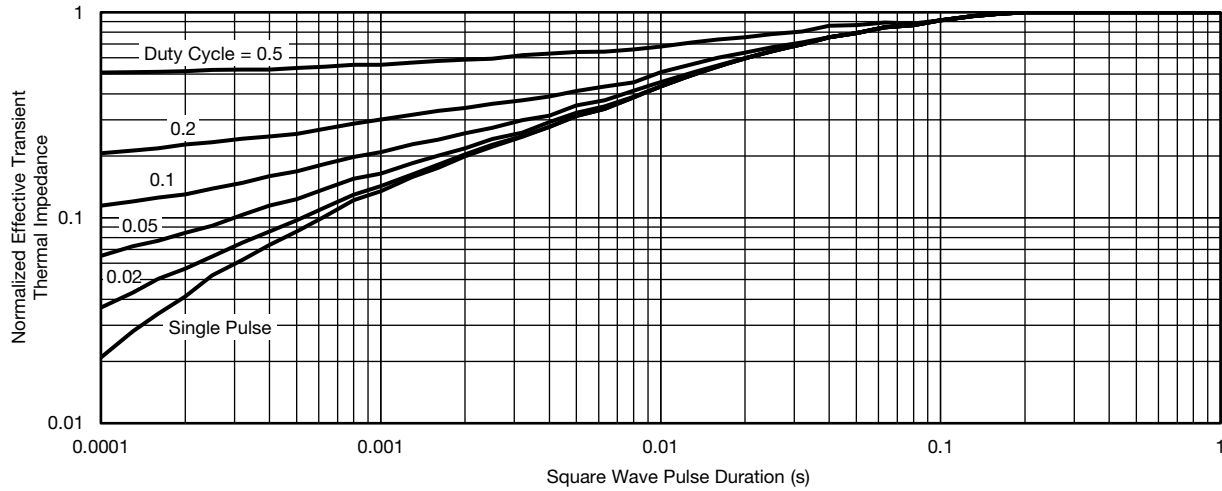
Transconductance



Safe Operating Area, Junction-to-Ambient

**Current Derating <sup>a</sup>****Drain Source Breakdown vs. Junction Temperature** **$I_{DAV}$  vs. Time****Note**

- a. The power dissipation  $P_D$  is based on  $T_J$  max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

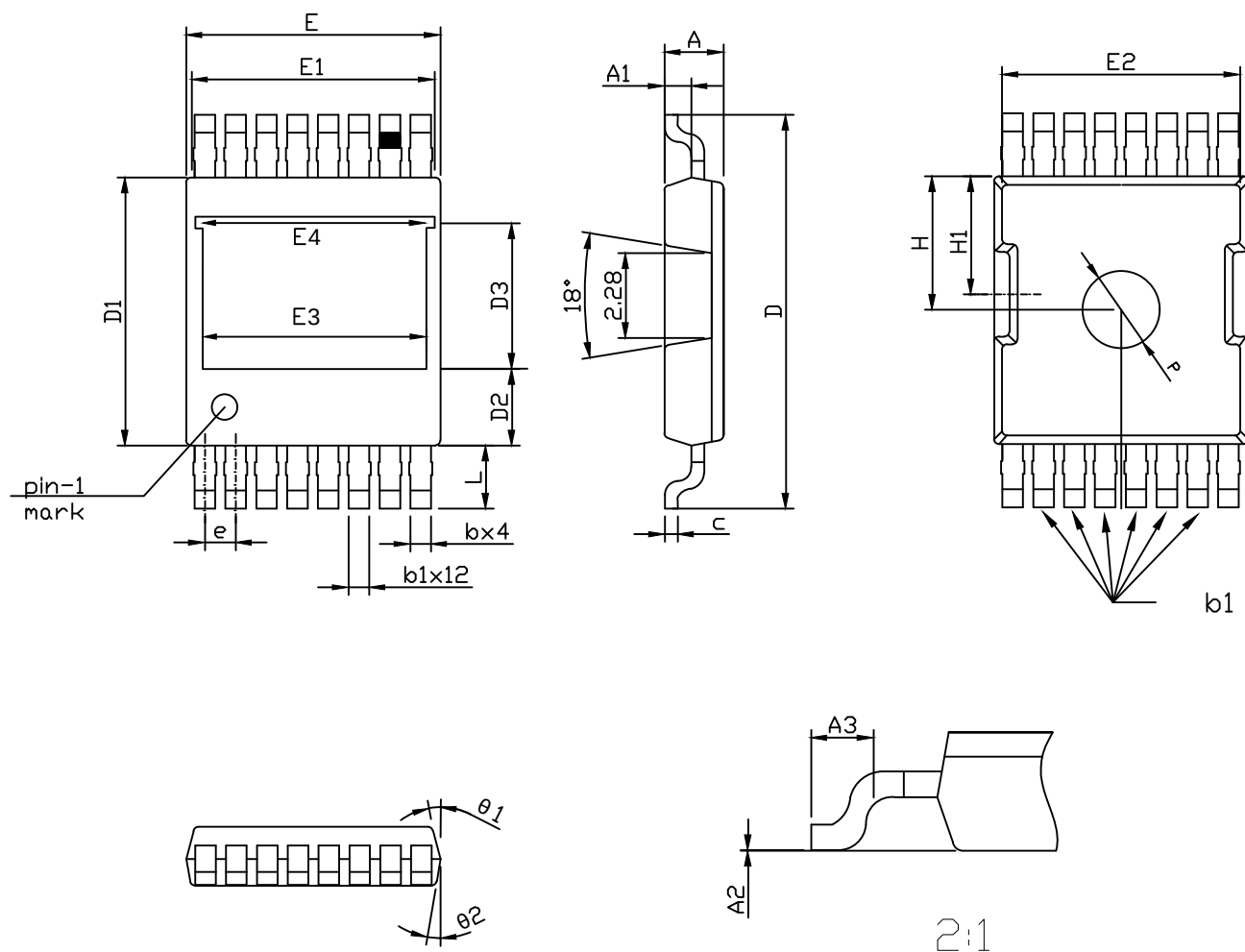
**THERMAL RATINGS** ( $T_C = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)


**Normalized Thermal Transient Impedance, Junction-to-Case**

**Note**

- The characteristics shown in the two graphs
    - Normalized Transient Thermal Impedance Junction to Ambient ( $25\text{ }^{\circ}\text{C}$ )
    - Normalized Transient Thermal Impedance Junction to Case ( $25\text{ }^{\circ}\text{C}$ )
- are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

## Package Outlines



UNIT : mm

| SYMBOLS | A     | A1   | A2      | A3      | b       | b1      | C       | D       |
|---------|-------|------|---------|---------|---------|---------|---------|---------|
| MIN     | 2.25  | 1.00 | 0.01    | 1.50REF | 0.68    | 0.75    | 0.45    | 14.80   |
| NOM     | 2.30  | 1.04 | 0.08    |         | 0.70    | 0.85    | 0.50    | 15.00   |
| MAX     | 2.35  | 1.08 | 0.16    |         | 0.74    | 0.95    | 0.55    | 15.20   |
| SYMBOLS | D1    | D2   | D3      | E       | E1      | E2      | E3      | E4      |
| MIN     | 10.00 | 2.40 | 5.77REF | 9.70    | 9.46REF | 9.25REF | 8.25REF | 8.70REF |
| NOM     | 10.10 | 2.60 |         | 9.90    |         |         |         |         |
| MAX     | 10.30 | 2.80 |         | 10.10   |         |         |         |         |
| SYMBOLS | e     | H    | H1      | L       | P       | φ1      | φ2      |         |
| MIN     | 1.18  | 5.00 | 4.40    | 2.40    | 2.80    | 7 °     | 7 °     |         |
| NOM     | 1.20  | 5.20 | 4.60    | 2.45    | 3.00    | -       | -       |         |
| MAX     | 1.22  | 5.40 | 4.80    | 2.50    | 3.20    | 9 °     | 9 °     |         |

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